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TL081, TL081A, TL081B, TL082, TL082A, TL082B TL084, TL084A, TL084B JFET-INPUT OPERATIONAL AMPLIFIERS

SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

- Low Power Consumption
- Wide Common-Mode and Differential Voltage Ranges
- Low Input Bias and Offset Currents
- Output Short-Circuit Protection
- Low Total Harmonic Distortion . . . 0.003% Typ
- High Input Impedance . . . JFET-Input Stage
- Latch-Up-Free Operation
- High Slew Rate . . . 13 V/ μ s Typ
- Common-Mode Input Voltage Range Includes V_{CC+}

description/ordering information

The TL08x JFET-input operational amplifier family is designed to offer a wider selection than any previously developed operational amplifier family. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in a monolithic integrated circuit. The devices feature high slew rates, low input bias and offset currents, and low offset-voltage temperature coefficient. Offset adjustment and external compensation options are available within the TL08x family.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from –40°C to 85°C. The Q-suffix devices are characterized for operation from –40°C to 125°C. The M-suffix devices are characterized for operation over the full military temperature range of –55°C to 125°C.

ORDERING INFORMATION

T_J	V_{IOmax} AT 25°C	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	15 mV	PDIP (P)	Tube of 50	TL081CP	TL081CP
			Tube of 50	TL082CP	TL082CP
		PDIP (N)	Tube of 25	TL084CN	TL084CN
		SOIC (D)	Tube of 75	TL081CD	TL081C
			Reel of 2500	TL081CDR	
			Tube of 75	TL082CD	TL082C
			Reel of 2500	TL082CDR	
			Tube of 50	TL084CD	TL084C
			Reel of 2500	TL084CDR	
		SOP (PS)	Reel of 2000	TL081CPSR	T081
			Reel of 2000	TL082CPSR	T082
		SOP (NS)	Reel of 2000	TL084CNSR	TL084
		TSSOP (PW)	Tube of 150	TL082CPW	T082
			Reel of 2000	TL082CPWR	
			Tube of 90	TL084CPW	T084
			Reel of 2000	TL084CPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

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description/ordering information (continued)

ORDERING INFORMATION

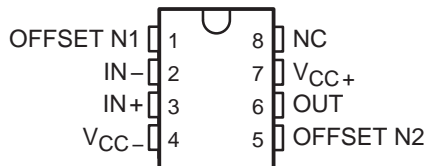
T _J	V _{IO} max AT 25°C	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	6 mV	PDIP (P)	Tube of 50	TL081ACP	TL081ACP
			Tube of 50	TL082ACP	TL082ACP
		PDIP (N)	Tube of 25	TL084ACN	TL084ACN
		SOIC (D)	Tube of 75	TL081ACD	081AC
			Reel of 2500	TL081ACDR	
			Tube of 75	TL082ACD	082AC
			Reel of 2500	TL082ACDR	
		SOIC (D)	Tube of 50	TL084ACD	TL084AC
	Reel of 2500		TL084ACDR		
	SOP (PS)	Reel of 2000	TL082ACPSR	T082A	
	SOP (NS)	Reel of 2000	TL084ACNSR	TL084A	
	3 mV	PDIP (P)	Tube of 50	TL081BCP	TL081BCP
			Tube of 50	TL082BCP	TL082BCP
		PDIP (N)	Tube of 25	TL084BCN	TL084BCN
		SOIC (D)	Tube of 75	TL081BCD	081BC
			Reel of 2500	TL081BCDR	
Tube of 75			TL082BCD	082BC	
Reel of 2500			TL082BCDR		
SOIC (D)		Tube of 50	TL084BCD	TL084BC	
	Reel of 2500	TL084BCDR			
-40°C to 85°C	6 mV	PDIP (P)	Tube of 50	TL081IP	TL081IP
			Tube of 50	TL082IP	TL082IP
		PDIP (N)	Tube of 25	TL084IN	TL081IN
		SOIC (D)	Tube of 75	TL081ID	TL081I
			Reel of 2500	TL081IDR	
			Tube of 75	TL082ID	TL082I
			Reel of 2500	TL082IDR	
		SOIC (D)	Tube of 50	TL084ID	TL084I
			Reel of 2500	TL084IDR	
		TSSOP (PW)	Reel of 2000	TL082IPWR	Z082
-40°C to 125°C	9 mV	SOIC (D)	Tube of 50	TL084QD	TL084QD
			Reel of 2500	TL084QDR	
-55°C to 125°C	9 mV	CDIP (J)	Tube of 25	TL084MJ	TL084MJ
		LCCC (FK)	Reel of 55	TL084FK	TL084FK
	6 mV	CDIP (JG)	Tube of 50	TL082MJG	TL082MJG
		LCCC (FK)	Tube of 55	TL082MFK	TL082MFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

TL081, TL081A, TL081B, TL082, TL082A, TL082B TL084, TL084A, TL084B JFET-INPUT OPERATIONAL AMPLIFIERS

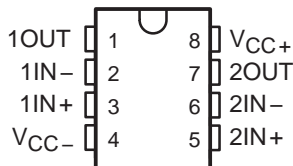
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TL081, TL081A, TL081B
D, P, OR PS PACKAGE
(TOP VIEW)

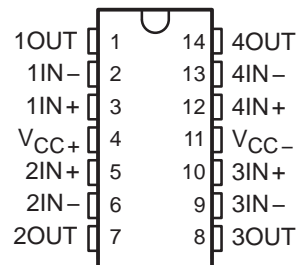


NC – No internal connection

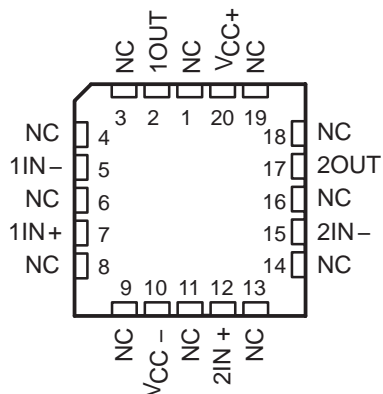
TL082, TL082A, TL082B
D, JG, P, PS, OR PW PACKAGE
(TOP VIEW)



TL084, TL084A, TL084B
D, J, N, NS, OR PW PACKAGE
(TOP VIEW)

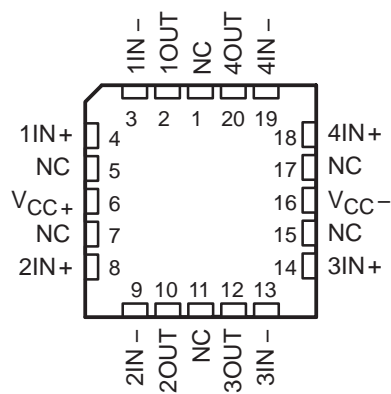


TL082M . . . FK PACKAGE
(TOP VIEW)



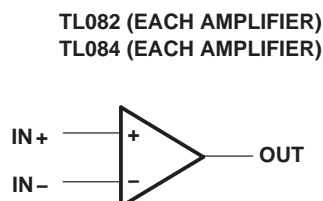
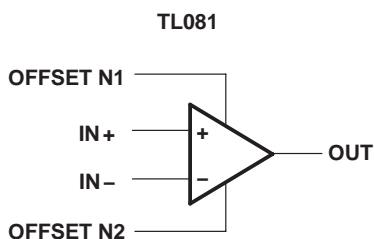
NC – No internal connection

TL084M . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

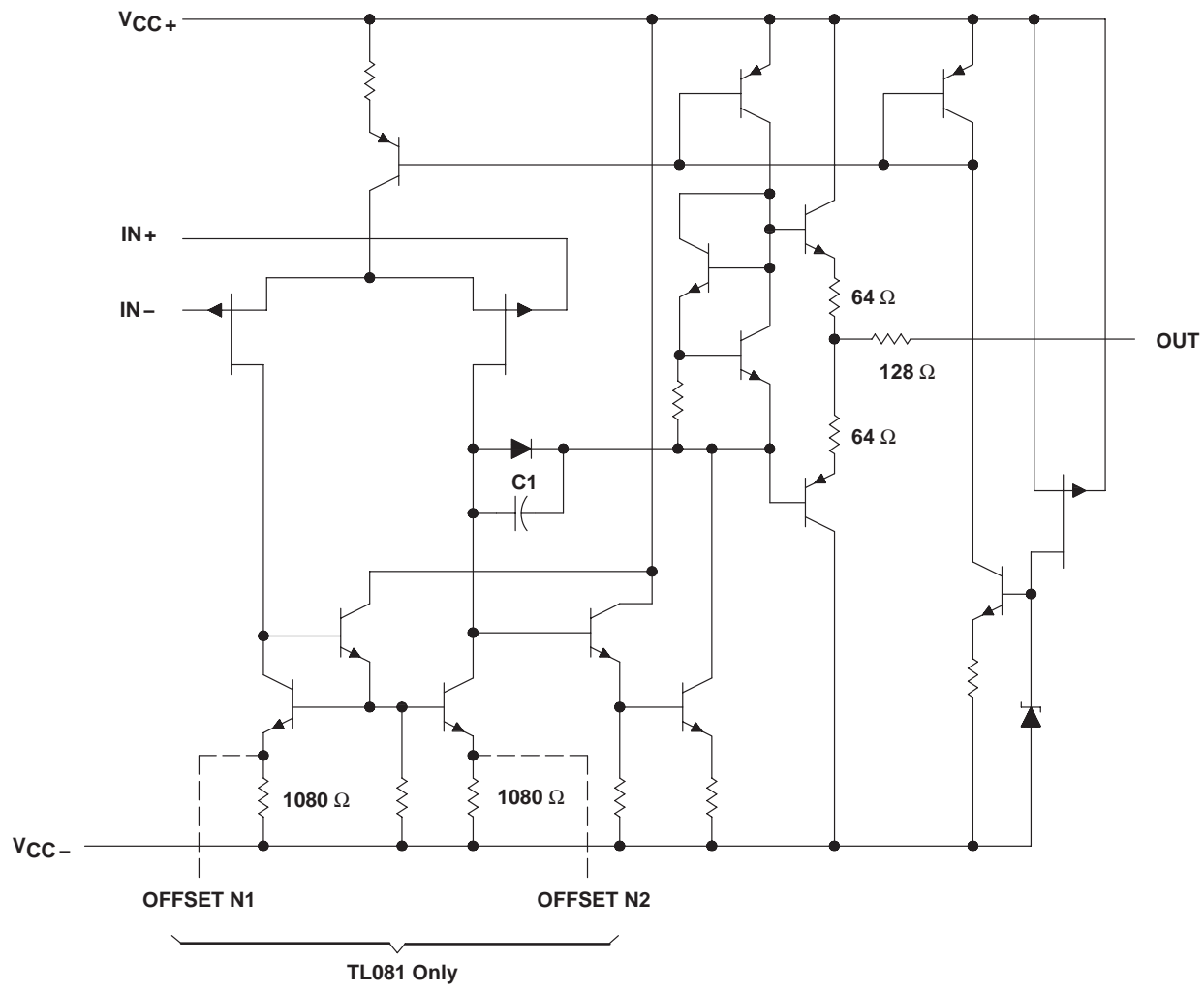
symbols



**TL081, TL081A, TL081B, TL082, TL082A, TL082B
 TL084, TL084A, TL084B
 JFET-INPUT OPERATIONAL AMPLIFIERS**

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schematic (each amplifier)



Component values shown are nominal.



TL081, TL081A, TL081B, TL082, TL082A, TL082B TL084, TL084A, TL084B JFET-INPUT OPERATIONAL AMPLIFIERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

	TL08_C TL08_AC TL08_BC	TL08_I	TL084Q	TL08_M	UNIT
Supply voltage, V_{CC+} (see Note 1)	18	18	18	18	V
Supply voltage V_{CC-} (see Note 1)	-18	-18	-18	-18	V
Differential input voltage, V_{ID} (see Note 2)	± 30	± 30	± 30	± 30	V
Input voltage, V_I (see Notes 1 and 3)	± 15	± 15	± 15	± 15	V
Duration of output short circuit (see Note 4)	Unlimited	Unlimited	Unlimited	Unlimited	
Continuous total power dissipation	See Dissipation Rating Table				
Operating free-air temperature range, T_A	0 to 70	-40 to 85	-40 to 125	-55 to 125	$^{\circ}\text{C}$
Package thermal impedance, θ_{JA} (see Notes 5 and 6)	D package (8-pin)	97	97		$^{\circ}\text{C}/\text{W}$
	D package (14-pin)	86	86		
	N package (14-pin)	76	76		
	NS package (14-pin)	80			
	P package (8-pin)	85	85		
	PS package (8-pin)	95	95		
	PW package (8-pin)	149			
	PW package (14-pin)	113	113		
Operating virtual junction temperature	150	150	150	150	$^{\circ}\text{C}$
Case temperature for 60 seconds, T_C	FK package			260	$^{\circ}\text{C}$
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds	J or JG package			300	$^{\circ}\text{C}$
Storage temperature range, T_{stg}	-65 to 150	-65 to 150	-65 to 150	-65 to 150	$^{\circ}\text{C}$

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
- All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 - Differential voltages are at $IN+$ with respect to $IN-$.
 - The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
 - Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150 $^{\circ}\text{C}$ can affect reliability.
 - The package thermal impedance is calculated in accordance with JESD 51-7.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^{\circ}\text{C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70^{\circ}\text{C}$ POWER RATING	$T_A = 85^{\circ}\text{C}$ POWER RATING	$T_A = 125^{\circ}\text{C}$ POWER RATING
D (14 pin)	680 mW	7.6 mW/ $^{\circ}\text{C}$	60 $^{\circ}\text{C}$	604 mW	490 mW	186 mW
FK	680 mW	11.0 mW/ $^{\circ}\text{C}$	88 $^{\circ}\text{C}$	680 mW	680 mW	273 mW
J	680 mW	11.0 mW/ $^{\circ}\text{C}$	88 $^{\circ}\text{C}$	680 mW	680 mW	273 mW
JG	680 mW	8.4 mW/ $^{\circ}\text{C}$	69 $^{\circ}\text{C}$	672 mW	546 mW	210 mW



**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

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electrical characteristics, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TA†	TL081C TL082C TL084C			TL081AC TL082AC TL084AC			TL081BC TL082BC TL084BC			TL081I TL082I TL084I			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V _{IO}	Input offset voltage V _O = 0 R _S = 50 Ω	25°C	3	15	6	3	6	2	3	3	6	3	6	mV	
		Full range		20	7.5		5			5		9			
α _{VIO}	Temperature coefficient of input offset voltage V _O = 0 R _S = 50 Ω	Full range	18			18			18			18		μV/°C	
		25°C	5	200	5	100	5	100	5	100	5	100			
I _{IO}	Input offset current ‡ V _O = 0	Full range		2	2		2	2		2	2		10	pA	
		25°C	30	400	30	200	30	200	30	200	30	200	30		200
I _{IB}	Input bias current ‡ V _O = 0	Full range		10	7		7	7		7	7		20	nA	
		25°C	±11	-12 to 15	±11	-12 to 15	±11	-12 to 15	±11	-12 to 15	±11	-12 to 15	±11		-12 to 15
V _{ICR}	Common-mode input voltage range	25°C	±12	±13.5	±12	±13.5	±12	±13.5	±12	±13.5	±12	±13.5	±12	V	
		Full range	±12		±12		±10	±12	±10	±12	±10	±12	±10		±12
V _{OM}	Maximum peak output voltage swing	25°C	±10	±12	±10	±12	±10	±12	±10	±12	±10	±12	±10	V	
		Full range	±10		±10		±10	±12	±10	±12	±10	±12	±10		±12
A _{V/D}	Large-signal differential voltage amplification V _O = ±10 V, R _L ≥ 2 kΩ	25°C	25	200	50	200	50	200	50	200	50	200	50	V/mV	
		Full range	15		25		25		25		25		25		
B ₁	Unity-gain bandwidth	25°C	3		3		3		3		3		MHz		
		25°C	10 ¹²		10 ¹²		10 ¹²		10 ¹²		10 ¹²			10 ¹²	
r _i	Input resistance	25°C	70	86	75	86	75	86	75	86	75	86	Ω		
		25°C	70	86	75	86	75	86	75	86	75	86			
CMRR	Common-mode rejection ratio	25°C	70	86	75	86	75	86	75	86	75	86	dB		
		25°C	70	86	75	86	75	86	75	86	75	86			
kSVR	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	25°C	70	86	75	86	75	86	75	86	75	86	dB		
		25°C	70	86	75	86	75	86	75	86	75	86			
I _{CC}	Supply current (per amplifier)	25°C	1.4	2.8	1.4	2.8	1.4	2.8	1.4	2.8	1.4	2.8	mA		
		25°C	1.4	2.8	1.4	2.8	1.4	2.8	1.4	2.8	1.4	2.8			
V _{O1} /V _{O2}	Crosstalk attenuation	25°C	120		120		120		120		120		dB		
		25°C	120		120		120		120		120				

† All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range for T_A is 0°C to 70°C for TL08_C, TL08_AC, TL08_BC and -40°C to 85°C for TL08_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.



**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

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electrical characteristics, $V_{CC\pm} = \pm 15\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	T_A	TL081M, TL082M			TL084Q, TL084M			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0, R_S = 50\ \Omega$	25°C	3	6		3	9	mV	
		Full range			9		15		
α_{VIO} Temperature coefficient of input offset voltage	$V_O = 0, R_S = 50\ \Omega$	Full range	18			18			$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current‡	$V_O = 0$	25°C	5	100		5	100	pA	
		125°C	20			20			nA
I_{IB} Input bias current‡	$V_O = 0$	25°C	30	200		30	200	pA	
		125°C	50			50			nA
V_{ICR} Common-mode input voltage range		25°C	± 11	-12 to 15		± 11	-12 to 15	V	
V_{OM} Maximum peak output voltage swing	$R_L = 10\ \text{k}\Omega$	25°C	± 12	± 13.5		± 12	± 13.5	V	
	$R_L \geq 10\ \text{k}\Omega$	Full range	± 12		± 12				
	$R_L \geq 2\ \text{k}\Omega$		± 10	± 12	± 10	± 12			
A_{VD} Large-signal differential voltage amplification	$V_O = \pm 10\ \text{V}, R_L \geq 2\ \text{k}\Omega$	25°C	25	200		25	200	V/mV	
	$V_O = \pm 10\ \text{V}, R_L \geq 2\ \text{k}\Omega$	Full range	15		15				
B_1 Unity-gain bandwidth		25°C	3			3			MHz
r_i Input resistance		25°C	10^{12}			10^{12}			Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}, V_O = 0, R_S = 50\ \Omega$	25°C	80	86		80	86	dB	
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC} = \pm 15\ \text{V to } \pm 9\ \text{V}, V_O = 0, R_S = 50\ \Omega$	25°C	80	86		80	86	dB	
I_{CC} Supply current (per amplifier)	$V_O = 0, \text{ No load}$	25°C	1.4	2.8		1.4	2.8	mA	
V_{O1}/V_{O2} Crosstalk attenuation	$A_{VD} = 100$	25°C	120			120			dB

† All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperatures as close to the ambient temperature as possible.

operating characteristics, $V_{CC\pm} = \pm 15\ \text{V}, T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
SR Slew rate at unity gain	$V_I = 10\ \text{V}, R_L = 2\ \text{k}\Omega, C_L = 100\ \text{pF}, \text{ See Figure 1}$	8*	13		V/ μs	
	$V_I = 10\ \text{V}, R_L = 2\ \text{k}\Omega, C_L = 100\ \text{pF}, T_A = -55^\circ\text{C to } 125^\circ\text{C}, \text{ See Figure 1}$	5*				
t_r Rise time	$V_I = 20\ \text{mV}, R_L = 2\ \text{k}\Omega, C_L = 100\ \text{pF}, \text{ See Figure 1}$	0.05			μs	
Overshoot factor		20			%	
V_n Equivalent input noise voltage	$R_S = 20\ \Omega$	f = 1 kHz			$\text{nV}/\sqrt{\text{Hz}}$	
		f = 10 Hz to 10 kHz			μV	
I_n Equivalent input noise current	$R_S = 20\ \Omega, f = 1\ \text{kHz}$	0.01			$\text{pA}/\sqrt{\text{Hz}}$	
THD Total harmonic distortion	$V_{rms} = 6\ \text{V}, f = 1\ \text{kHz}$	$A_{VD} = 1, R_S \leq 1\ \text{k}\Omega, R_L \geq 2\ \text{k}\Omega,$	0.003			%

*On products compliant to MIL-PRF-38535, this parameter is not production tested.



**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

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operating characteristics, $V_{CC\pm} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR Slew rate at unity gain	$V_I = 10\text{ V}$, $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$, See Figure 1	8	13		$\text{V}/\mu\text{s}$
t_r Rise time	$V_I = 20\text{ mV}$, $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$, See Figure 1		0.05		μs
Overshoot factor			20		%
V_n Equivalent input noise voltage	$R_S = 20\ \Omega$	$f = 1\text{ kHz}$	18		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ Hz to } 10\text{ kHz}$	4		μV
I_n Equivalent input noise current	$R_S = 20\ \Omega$, $f = 1\text{ kHz}$		0.01		$\text{pA}/\sqrt{\text{Hz}}$
THD Total harmonic distortion	$V_{I\text{rms}} = 6\text{ V}$, $f = 1\text{ kHz}$, $A_{VD} = 1$, $R_S \leq 1\text{ k}\Omega$, $R_L \geq 2\text{ k}\Omega$,		0.003		%

PARAMETER MEASUREMENT INFORMATION

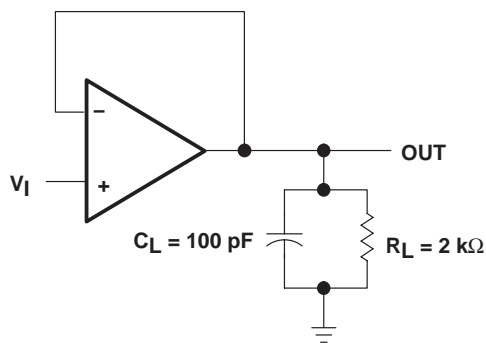


Figure 1

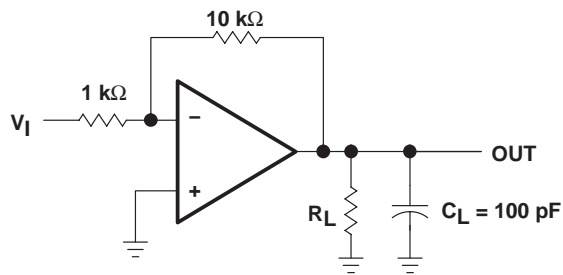


Figure 2

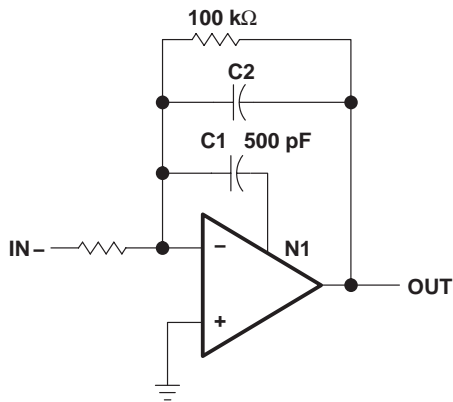


Figure 3

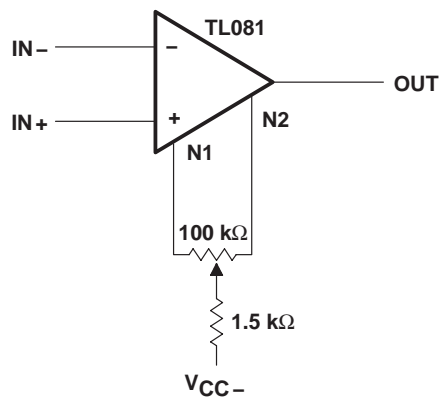


Figure 4

TYPICAL CHARACTERISTICS

Table of Graphs

		FIGURE
V _{OM}	Maximum peak output voltage	vs Frequency
		vs Free-air temperature
		vs Load resistance
		vs Supply voltage
AVD	Large-signal differential voltage amplification	vs Free-air temperature
		vs Frequency
	Differential voltage amplification	vs Frequency with feed-forward compensation
PD	Total power dissipation	vs Free-air temperature
I _{CC}	Supply current	vs Free-air temperature
		vs Supply voltage
I _{IB}	Input bias current	vs Free-air temperature
	Large-signal pulse response	vs Time
V _O	Output voltage	vs Elapsed time
CMRR	Common-mode rejection ratio	vs Free-air temperature
V _n	Equivalent input noise voltage	vs Frequency
THD	Total harmonic distortion	vs Frequency

**MAXIMUM PEAK OUTPUT VOLTAGE
 vs
 FREQUENCY**

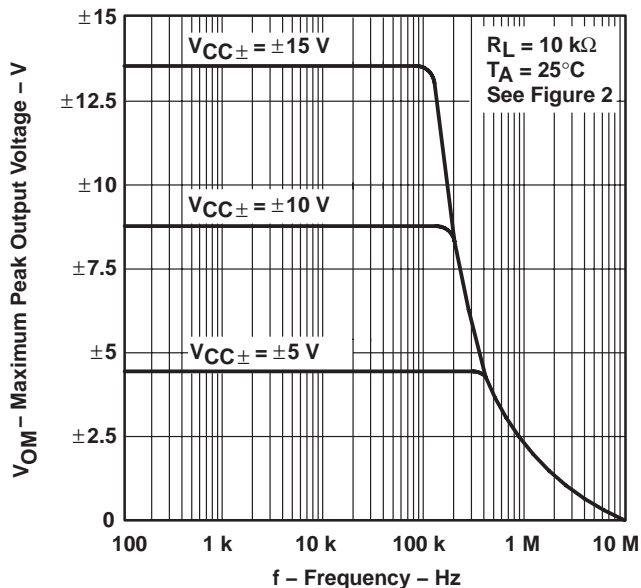


Figure 5

**MAXIMUM PEAK OUTPUT VOLTAGE
 vs
 FREQUENCY**

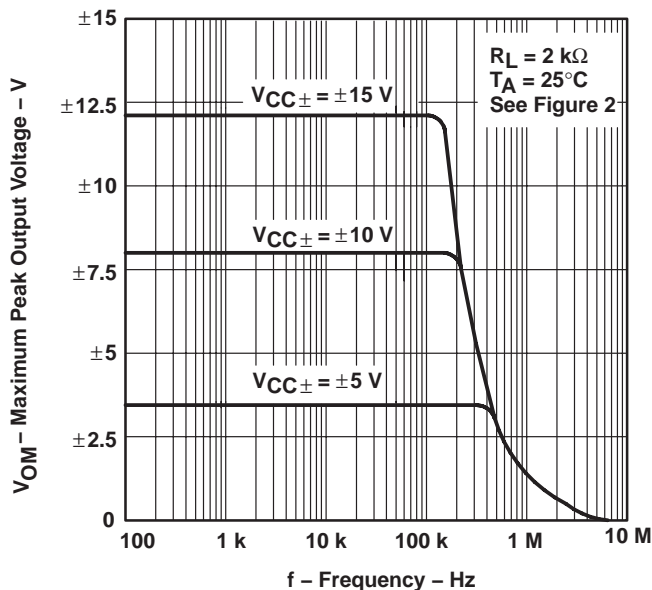


Figure 6

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

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TYPICAL CHARACTERISTICS†

**MAXIMUM PEAK OUTPUT VOLTAGE
vs
FREQUENCY**

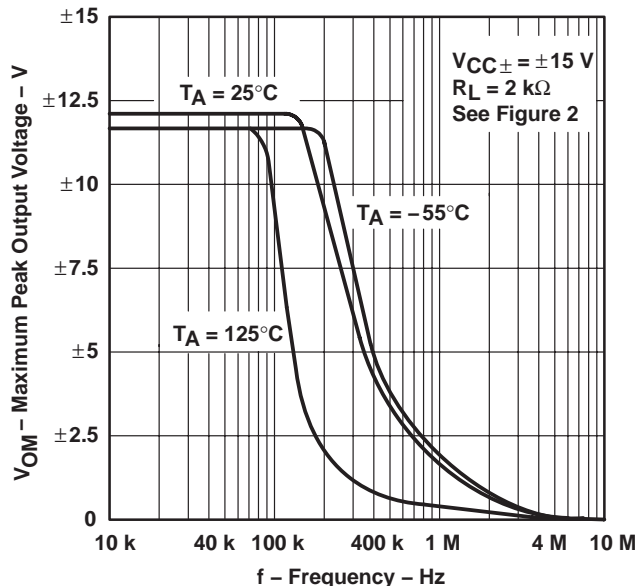


Figure 7

**MAXIMUM PEAK OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE**

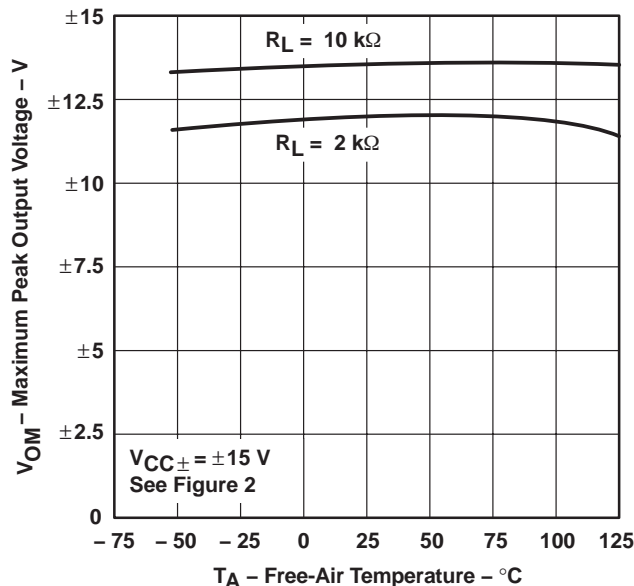


Figure 8

**MAXIMUM PEAK OUTPUT VOLTAGE
vs
LOAD RESISTANCE**

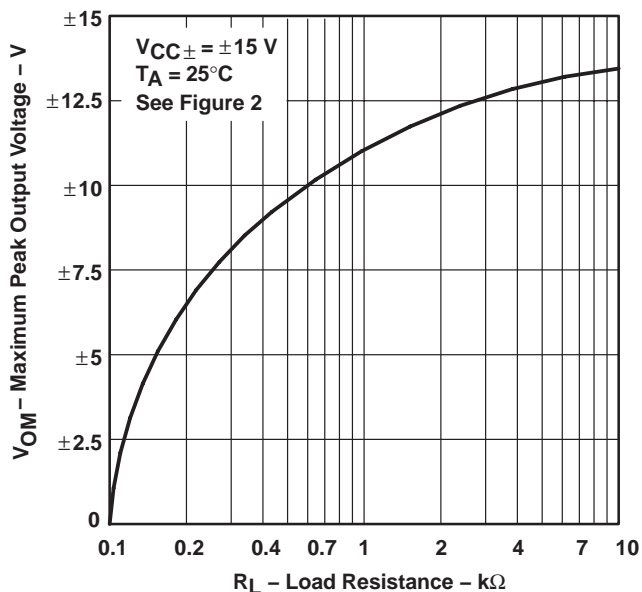


Figure 9

**MAXIMUM PEAK OUTPUT VOLTAGE
vs
SUPPLY VOLTAGE**

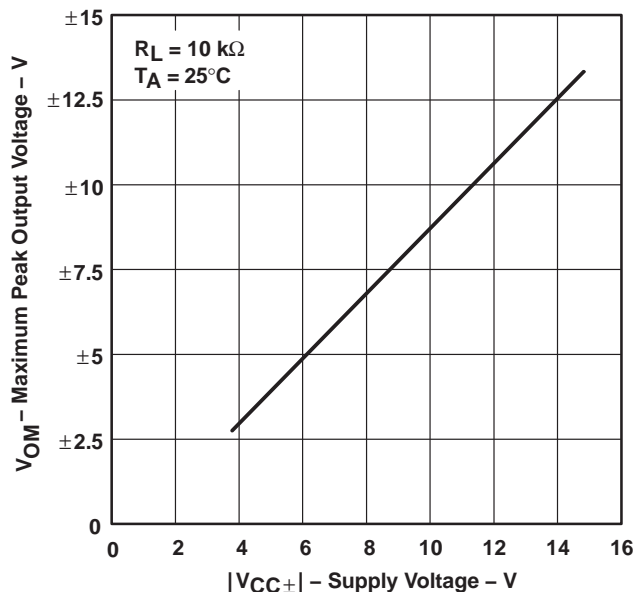


Figure 10

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS†

**LARGE-SIGNAL
 DIFFERENTIAL VOLTAGE AMPLIFICATION
 vs
 FREE-AIR TEMPERATURE**

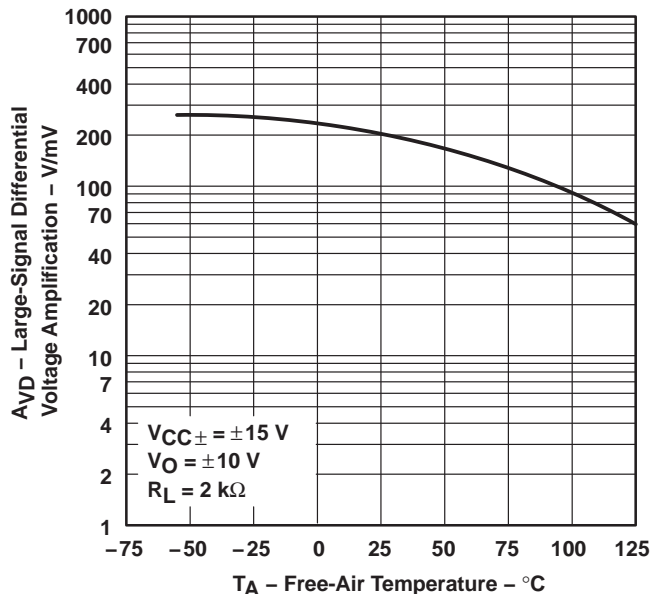


Figure 11

**LARGE-SIGNAL
 DIFFERENTIAL VOLTAGE AMPLIFICATION
 vs
 FREQUENCY**

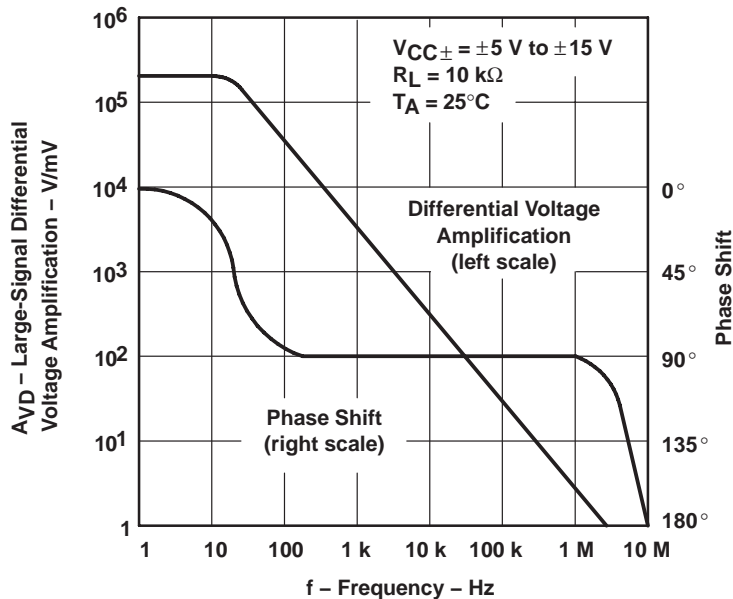


Figure 12

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

**DIFFERENTIAL VOLTAGE AMPLIFICATION
vs
FREQUENCY WITH FEED-FORWARD COMPENSATION**

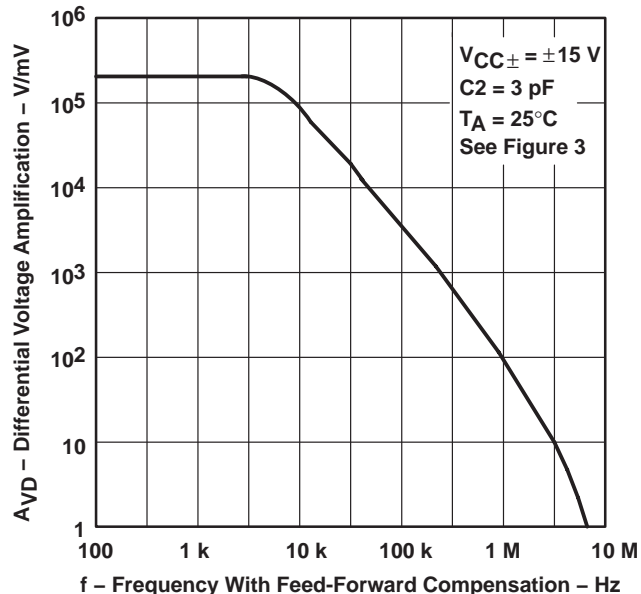


Figure 13

**TOTAL POWER DISSIPATION
vs
FREE-AIR TEMPERATURE**

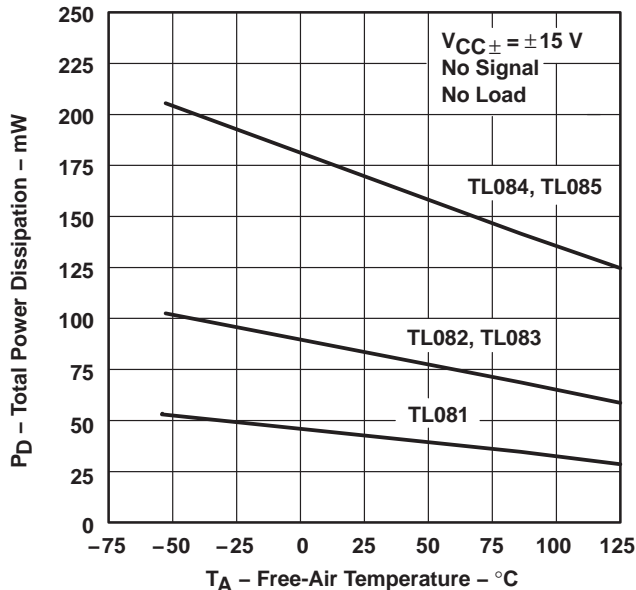


Figure 14

**SUPPLY CURRENT PER AMPLIFIER
vs
FREE-AIR TEMPERATURE**

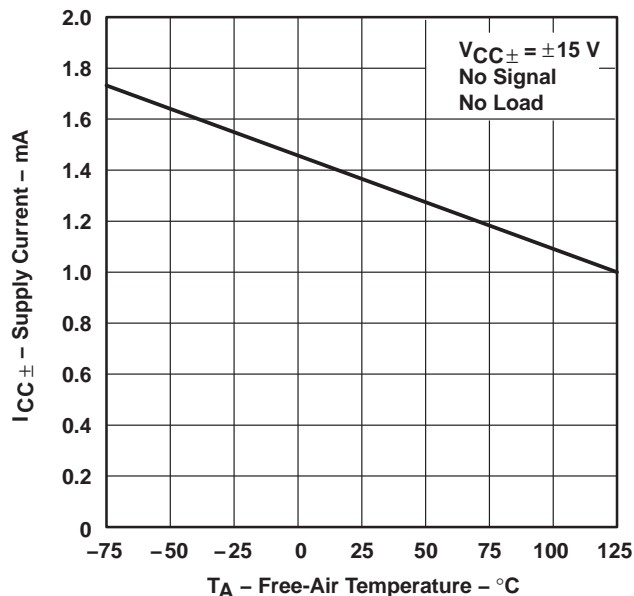


Figure 15

**SUPPLY CURRENT
vs
SUPPLY VOLTAGE**

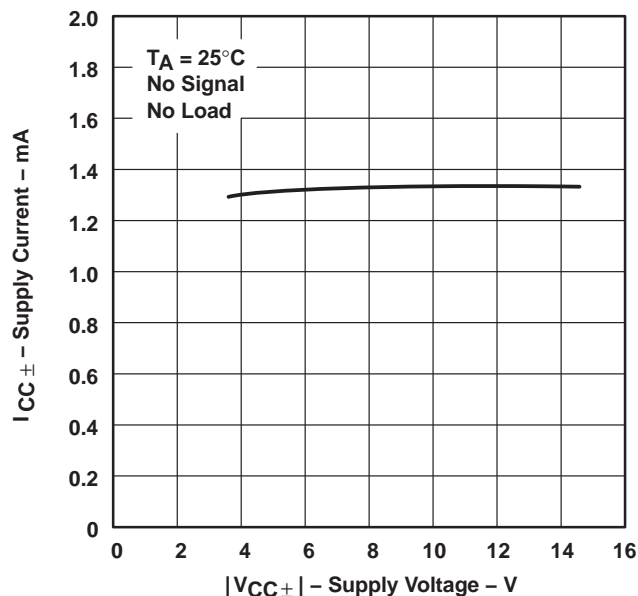
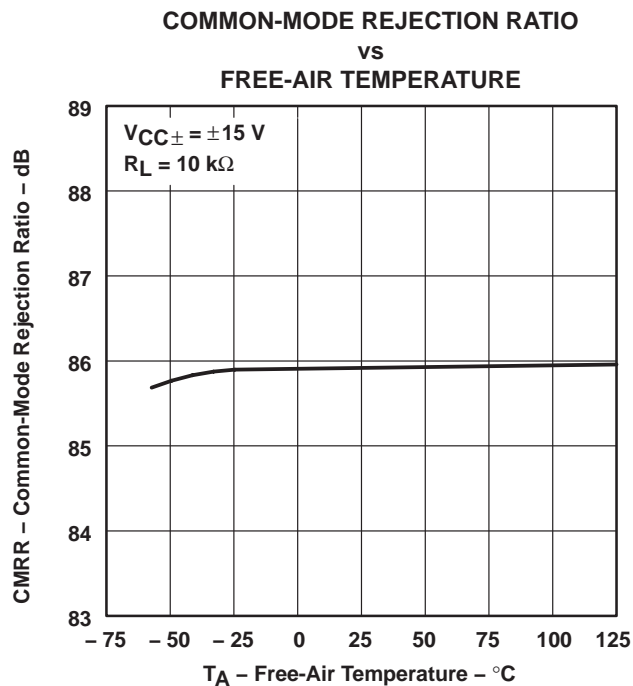
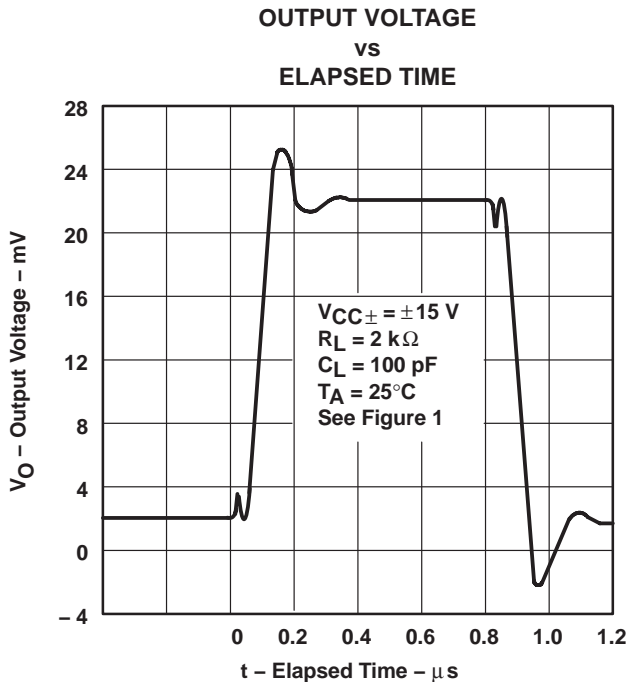
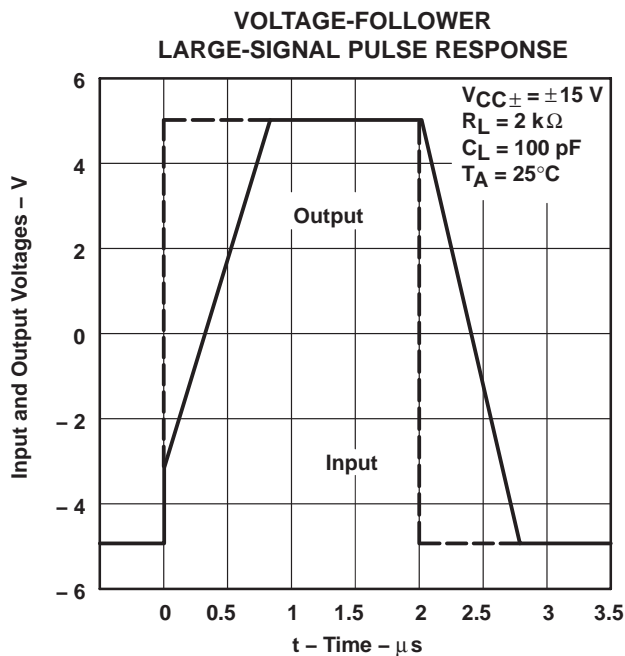
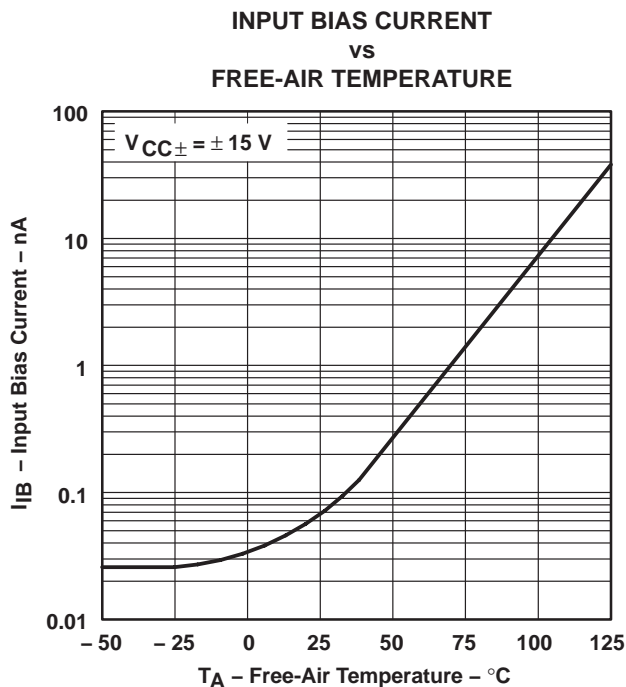


Figure 16

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS†



† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

**TL081, TL081A, TL081B, TL082, TL082A, TL082B
TL084, TL084A, TL084B
JFET-INPUT OPERATIONAL AMPLIFIERS**

SLOS081G – FEBRUARY 1977 – REVISED SEPTEMBER 2004

TYPICAL CHARACTERISTICS†

**EQUIVALENT INPUT NOISE VOLTAGE
VS
FREQUENCY**

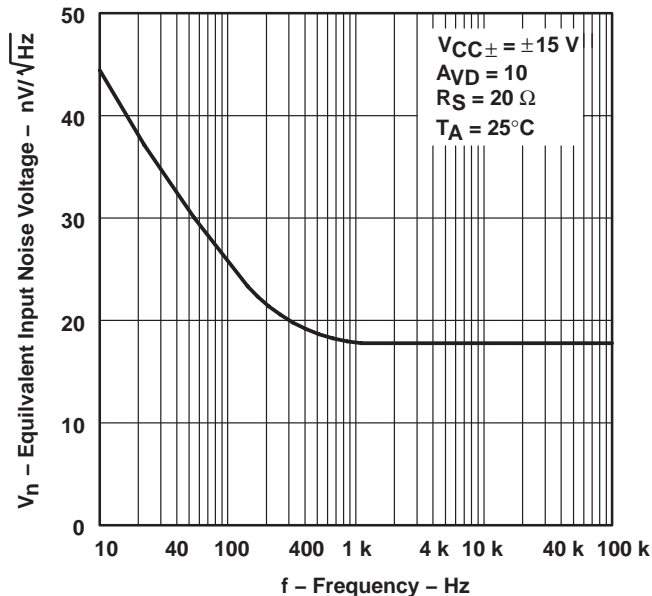


Figure 21

**TOTAL HARMONIC DISTORTION
VS
FREQUENCY**

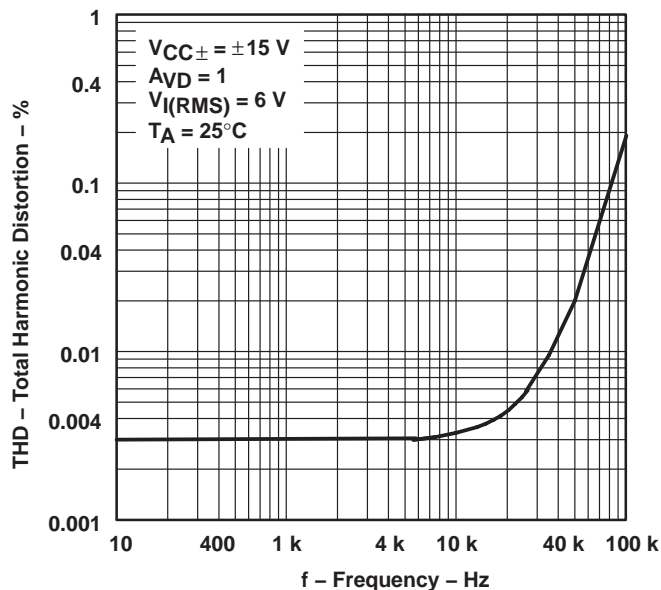


Figure 22

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

APPLICATION INFORMATION

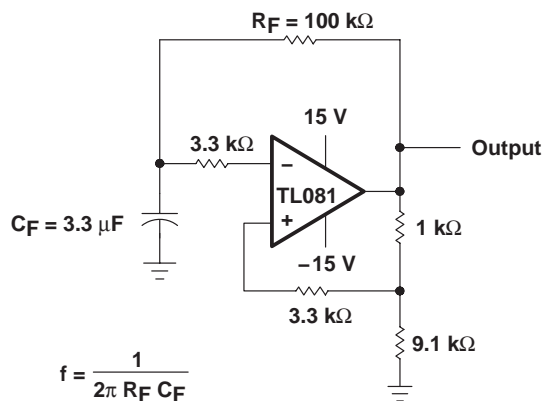


Figure 23

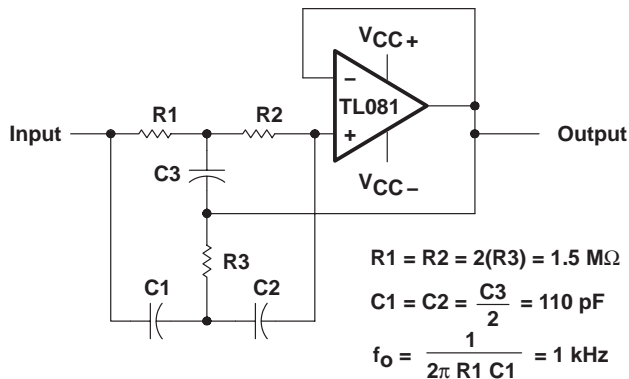


Figure 24

APPLICATION INFORMATION

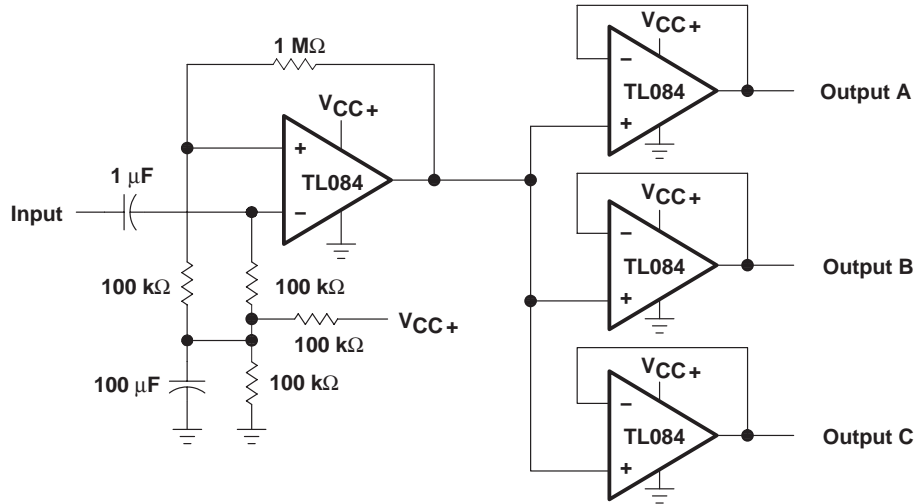
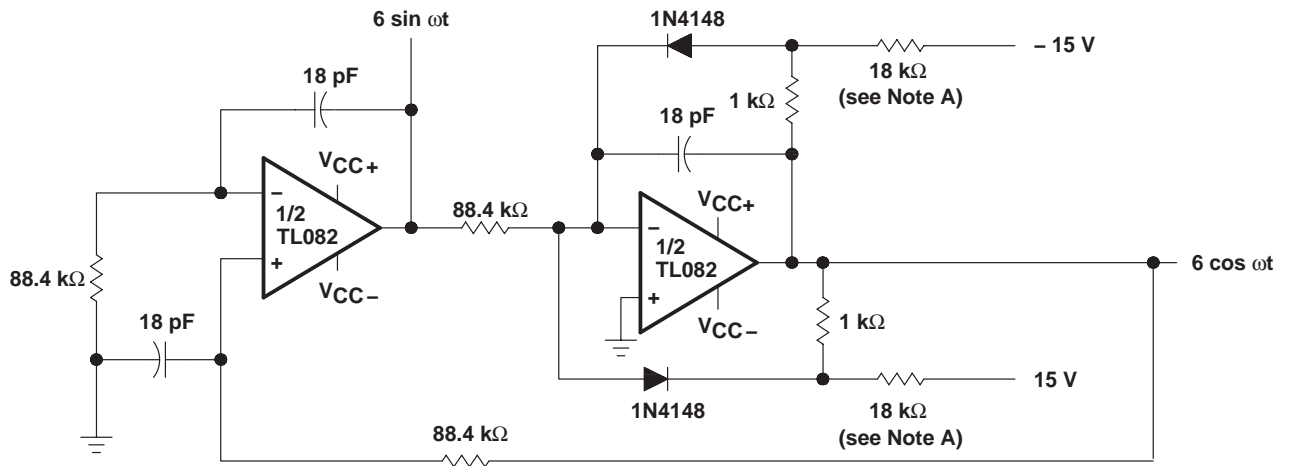


Figure 25. Audio-Distribution Amplifier



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 26. 100-KHz Quadrature Oscillator

APPLICATION INFORMATION

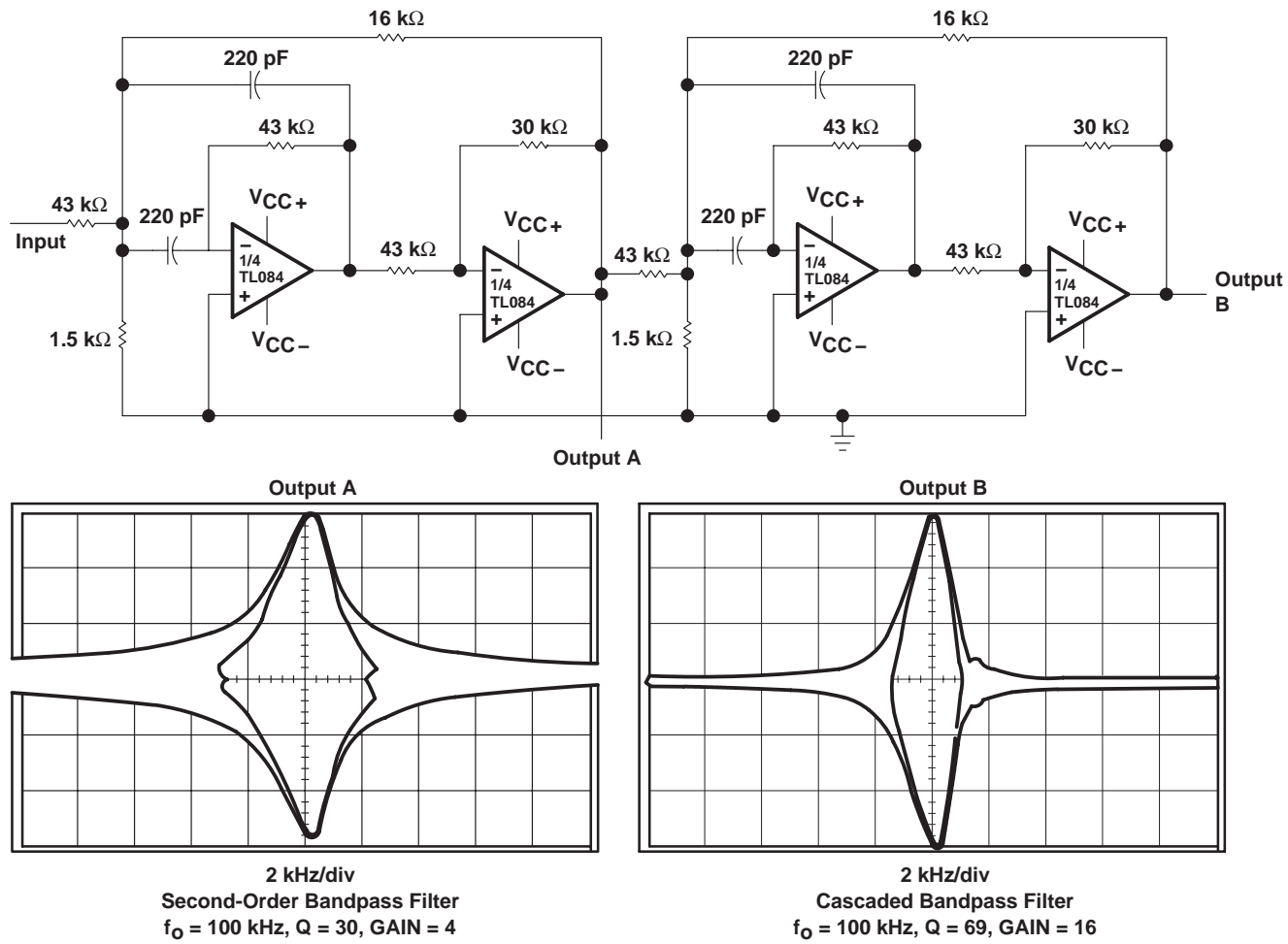


Figure 27. Positive-Feedback Bandpass Filter

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Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
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		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9851501Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9851501QPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9851503Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9851503QCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL081ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL081ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL081CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TL081ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL081IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL081MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL081MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL081MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL082ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
TL082BCDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL082CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TL082CPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082CPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL082IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TL082IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL082IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL082MFK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TL082MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL082MJG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL082MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
TL084ACD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084ACNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084ACNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ACNSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084BCDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL084BCN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084BCNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084CD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL084CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084CNSLE	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI
TL084CNSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CNSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
TL084CPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084CPWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084ID	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL084IJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
TL084IN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL084INE4	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
(RoHS)								
TL084MFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL084MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TL084MJ	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL084MJB	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
TL084QD	ACTIVE	SOIC	D	14	50	TBD	CU NIPDAU	Level-1-220C-UNLIM
TL084QDR	ACTIVE	SOIC	D	14	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

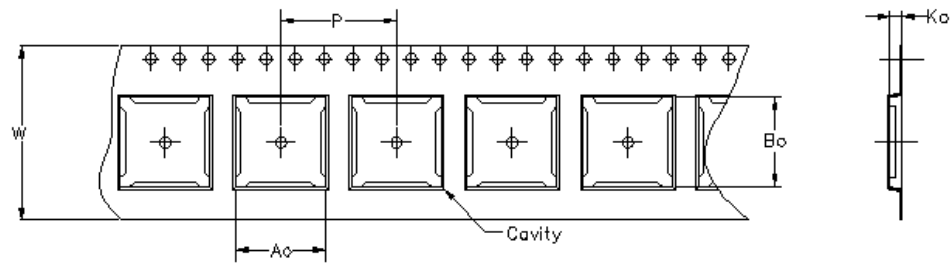
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

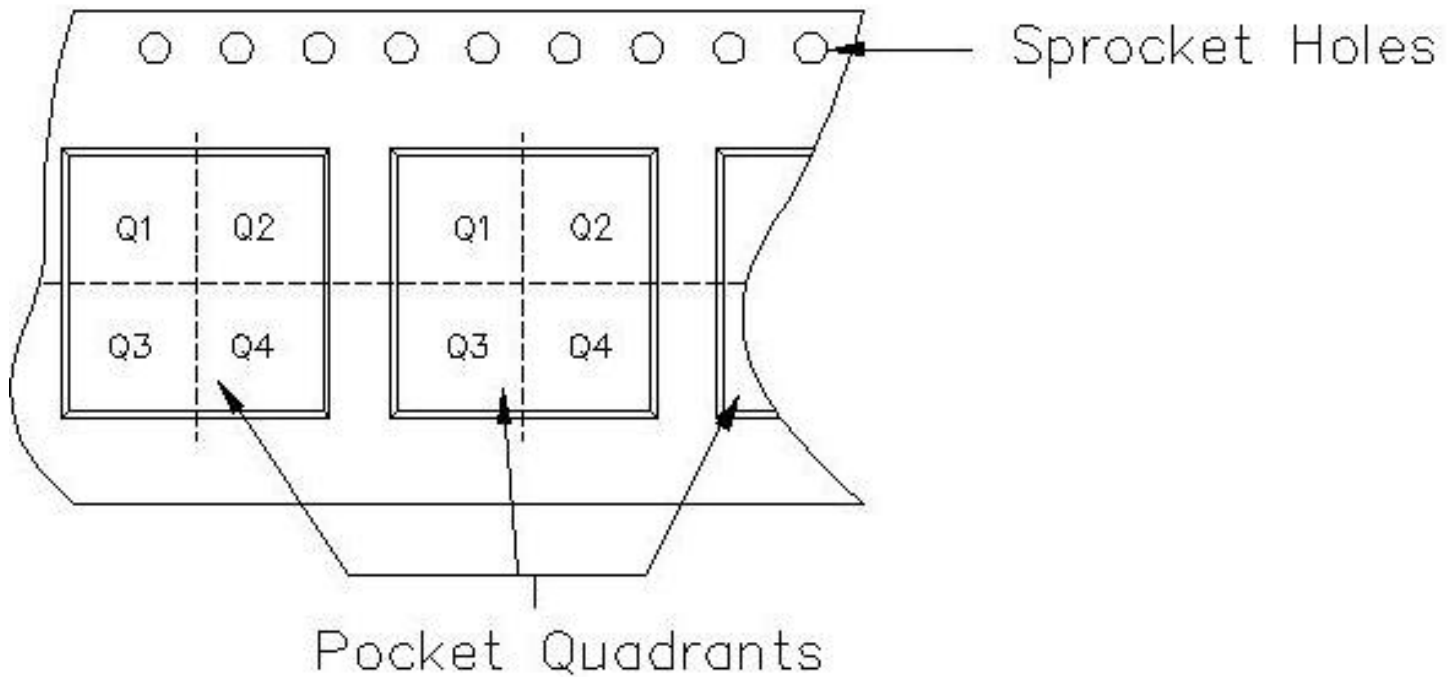
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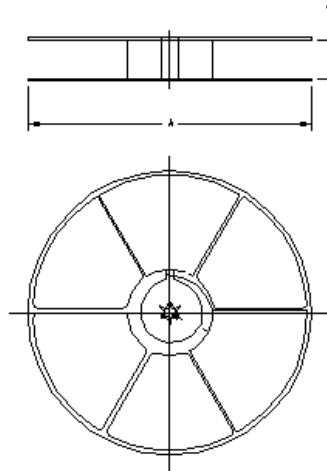
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



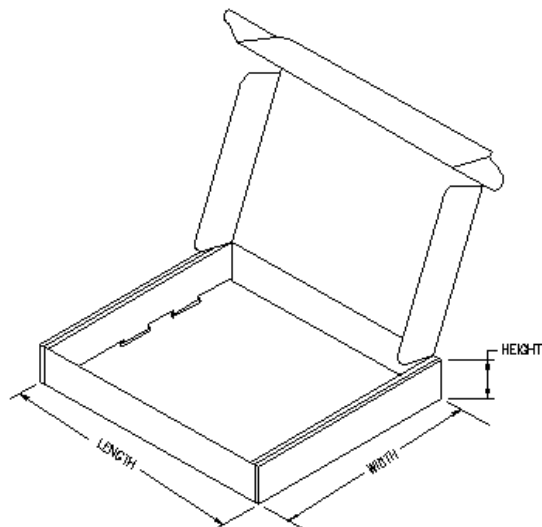
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL081ACDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL081BCDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL081CDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL081CPSR	PS	8	MLA	330	16	8.2	6.6	2.5	12	16	Q1
TL081IDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL082ACDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL082ACDR	D	8	MLA	330	12	6.4	5.2	2.1	8	12	Q1
TL082ACPSR	PS	8	MLA	330	16	8.2	6.6	2.5	12	16	Q1
TL082BCDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL082CDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL082CDR	D	8	MLA	330	12	6.4	5.2	2.1	8	12	Q1
TL082CPSR	PS	8	MLA	330	16	8.2	6.6	2.5	12	16	Q1
TL082CPWR	PW	8	MLA	330	12	7.0	3.6	1.6	8	12	Q1
TL082IDR	D	8	FMX	330	12	6.4	5.2	2.1	8	12	Q1
TL082IDR	D	8	MLA	330	12	6.4	5.2	2.1	8	12	Q1
TL082IPWR	PW	8	MLA	330	12	7.0	3.6	1.6	8	12	Q1
TL084ACDR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1
TL084ACDR	D	14	FMX	330	0	6.5	9.0	2.1	8	16	Q1
TL084ACNSR	NS	14	MLA	330	16	8.2	10.5	2.5	12	16	Q1
TL084BCDR	D	14	FMX	330	0	6.5	9.0	2.1	8	16	Q1
TL084CDR	D	14	FMX	330	0	6.5	9.0	2.1	8	16	Q1
TL084CNSR	NS	14	MLA	330	16	8.2	10.5	2.5	12	16	Q1
TL084CPWR	PW	14	MLA	330	12	7.0	5.6	1.6	8	12	Q1
TL084IDR	D	14	FMX	330	0	6.5	9.0	2.1	8	16	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
TL081ACDR	D	8	FMX	338.1	340.5	20.64
TL081BCDR	D	8	FMX	338.1	340.5	20.64
TL081CDR	D	8	FMX	338.1	340.5	20.64
TL081CPSR	PS	8	MLA	333.2	333.2	28.58
TL081IDR	D	8	FMX	338.1	340.5	20.64
TL082ACDR	D	8	FMX	338.1	340.5	20.64
TL082ACDR	D	8	MLA	338.1	340.5	20.64
TL082ACPSR	PS	8	MLA	333.2	333.2	28.58
TL082BCDR	D	8	FMX	338.1	340.5	20.64
TL082CDR	D	8	FMX	338.1	340.5	20.64
TL082CDR	D	8	MLA	338.1	340.5	20.64
TL082CPSR	PS	8	MLA	333.2	333.2	28.58
TL082CPWR	PW	8	MLA	338.1	340.5	20.64
TL082IDR	D	8	FMX	338.1	340.5	20.64
TL082IDR	D	8	MLA	338.1	340.5	20.64
TL082IPWR	PW	8	MLA	338.1	340.5	20.64
TL084ACDR	D	14	MLA	333.2	333.2	28.58
TL084ACDR	D	14	FMX	333.2	333.2	28.58
TL084ACNSR	NS	14	MLA	333.2	333.2	28.58
TL084BCDR	D	14	FMX	333.2	333.2	28.58
TL084CDR	D	14	FMX	333.2	333.2	28.58
TL084CNSR	NS	14	MLA	333.2	333.2	28.58
TL084CPWR	PW	14	MLA	338.1	340.5	20.64
TL084IDR	D	14	FMX	333.2	333.2	28.58



JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP1-T8

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

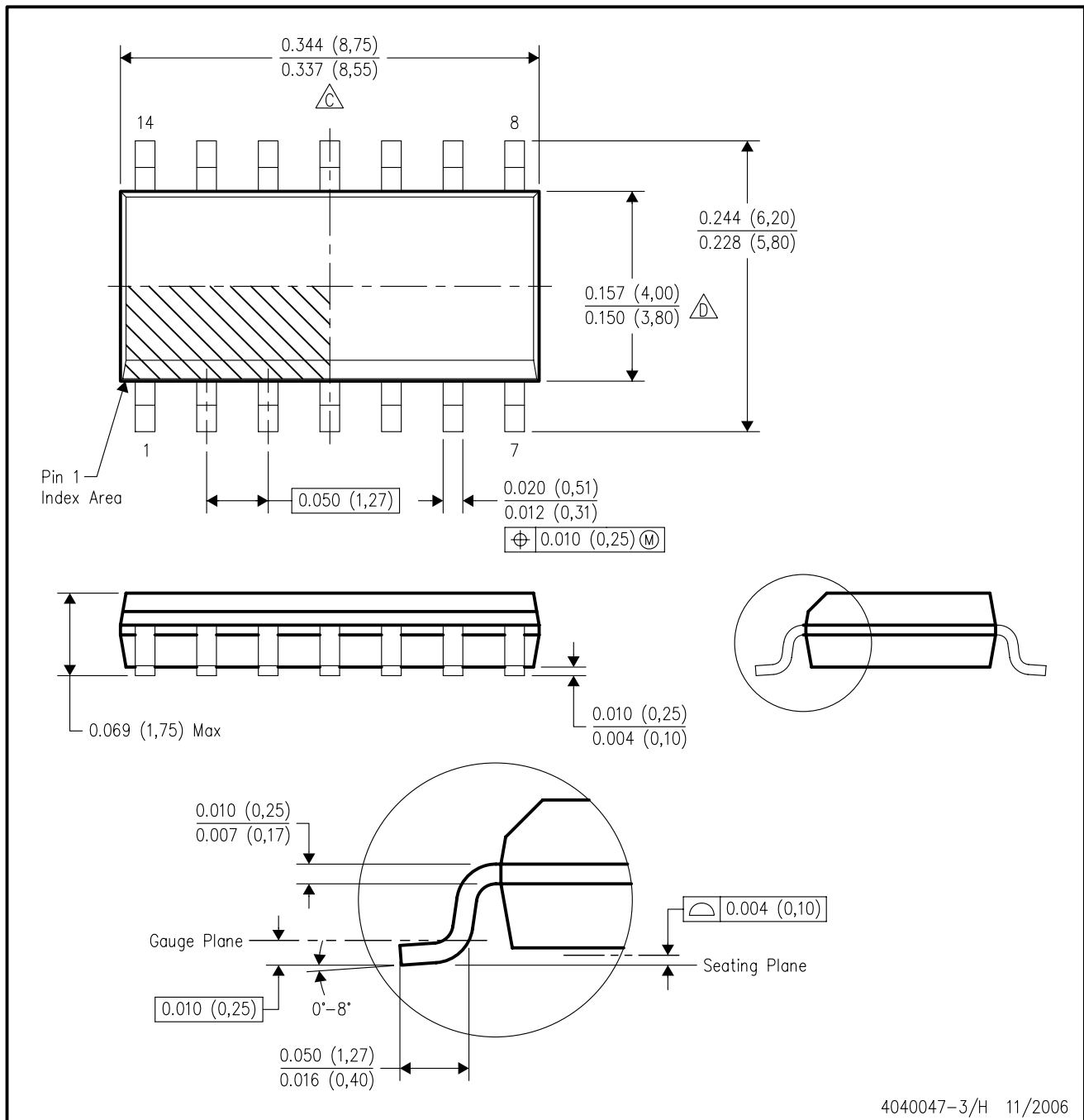
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

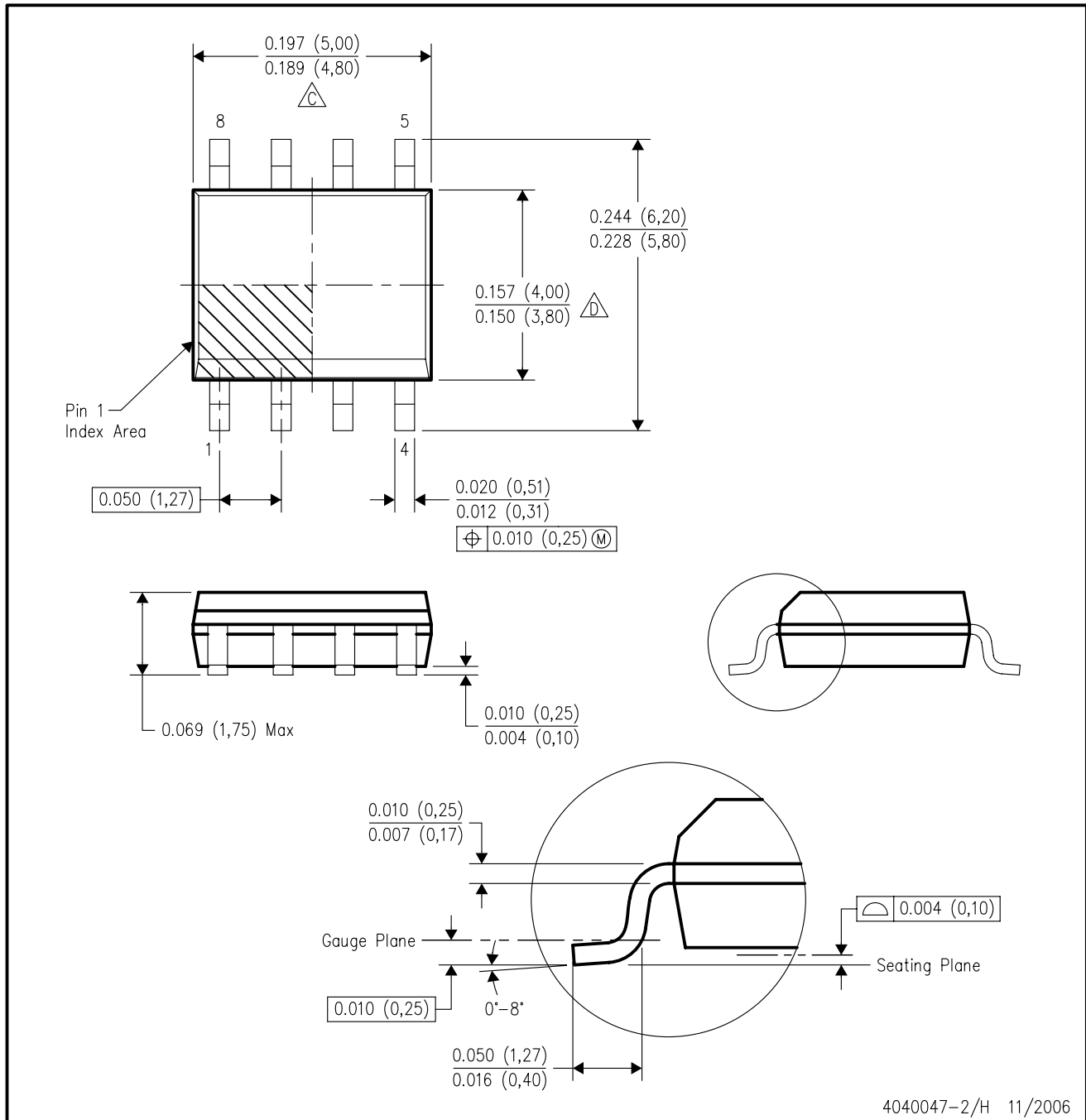


4040047-3/H 11/2006

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

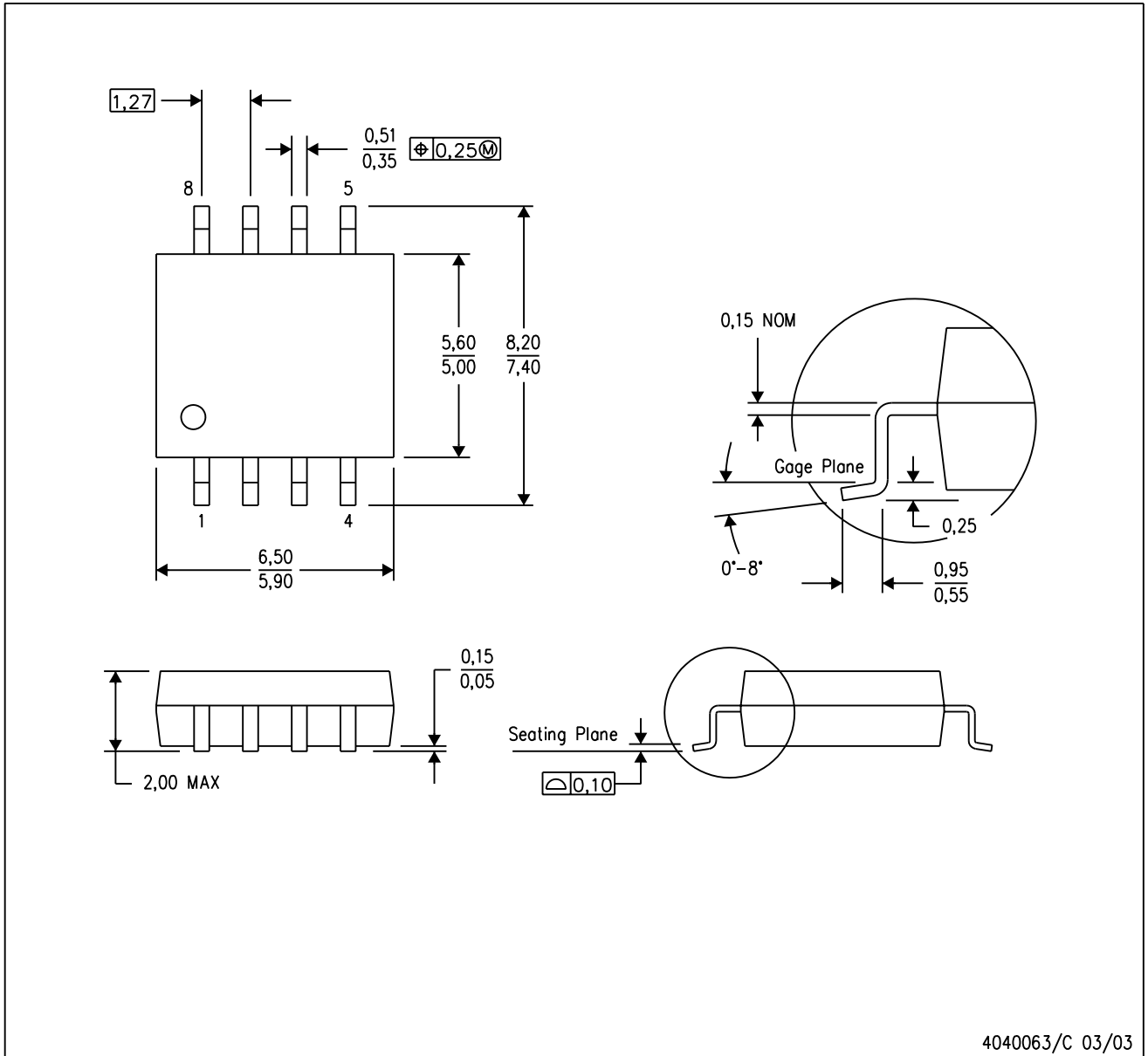


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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